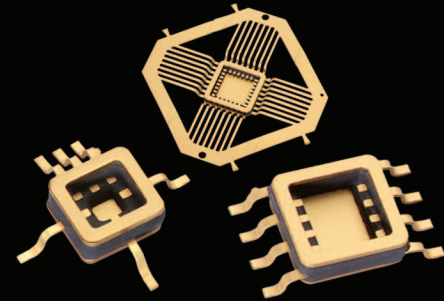
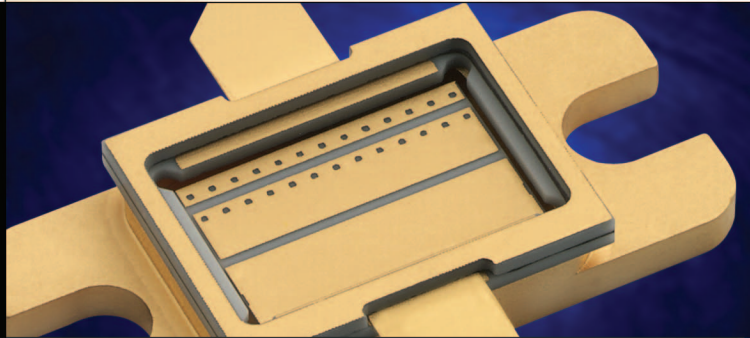




# POWER PACKAGES

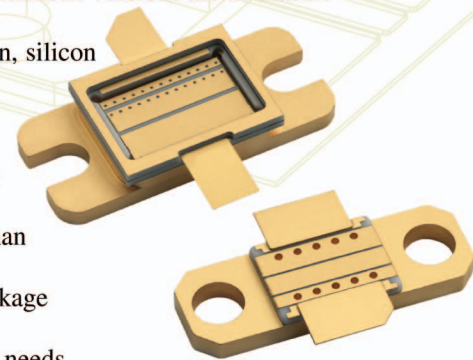
HIGH FREQUENCY  
AND  
HIGH SPEED  
PACKAGING



StratEdge power packages come in many shapes, sizes, and lead counts. One thing common to all of them is they are thermally enhanced packages designed for reliability. All materials used in the packages have matched coefficients of expansion to mitigate the inherent stresses of brazing dissimilar materials together. Our power packages can handle assembly temperatures up to 360 degrees Celsius. These packages incorporate copper composite bases and beryllium oxide (BeO) ceramic or copper heat spreaders for enhanced thermal dissipation. Hermetic and non-hermetic versions are available.

StratEdge power packages are used to package bipolar silicon, silicon carbide, gallium nitride, and other compound semiconductors. Specific power integrated circuits include microwave amplifiers, discrete transistors, and diodes where greater than 0.5 Watt power is consumed. The diversity of our power package product line makes certain we have the package that meets your needs.

Below are a few of our standard, open-tooled molded ceramic packages with copper composite bases. They can be provided as drop-ins (straight leads) or surface mounts (gull-wing formed leads). All give you a low cost way to package your high power device in a fully hermetic package.



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PN	Seal Ring Outside Dimensions	Pedestal Dimensions	Lid PN	Lead Count	Max Lead Count
G1010CT-1	.098" x .098"	.030" x .055"	CL1010	2	4
G1616CT-2	.166" x .166"	.070" x .090"	CL1616	8	12
G2121CT-1	.215" x .215"	.120" x .120"	CL2121	16	32
G2525CT-4	.270" x .270"	.150" x .150"	CL2525	24	32
G3838CT-1F	.375" x .375"	.260" x .290"	CL3838	14	24

Other custom configurations available upon request. Please consult factory.



S T R A T E D G E